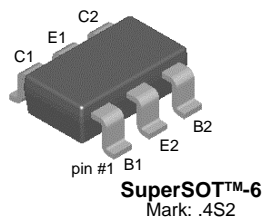


# FMBM5401

## PNP General Purpose Amplifier

- This device has matched dies in SuperSOT-6.



### Absolute Maximum Ratings\*

| Symbol         | Parameter  | Value     | Units |
|----------------|--|-----------|-------|
| $V_{CEO}$      | Collector-Emitter Voltage                        | -150      | V     |
| $V_{CBO}$      | Collector-Base Voltage                           | -160      | V     |
| $V_{EBO}$      | Emitter-Base Voltage                             | -5.0      | V     |
| $I_C$          | Collector Current - Continuous                   | -600      | mA    |
| $T_J, T_{STG}$ | Operating and Storage Junction Temperature Range | -55 ~ 150 | °C    |

\* These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

**Notes:**

- These ratings are based on a maximum junction temperature of 150 degrees C.
- These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations.

### Electrical Characteristics $T_C = 25^\circ\text{C}$ unless otherwise noted

| Symbol                     | Parameter  | Conditions  | Min. | Max        | Units               |
|----------------------------|--|---|------|------------|---------------------|
| <b>Off Characteristics</b> |  |   |      |            |                     |
| $BV_{CEO}$                 | Collector-Emitter Breakdown Voltage *                | $I_C = -1.0\text{mA}, I_B = 0$  | -150 |            | V                   |
| $BV_{CBO}$                 | Collector-Base Breakdown Voltage                     | $I_C = -100\mu\text{A}, I_E = 0$  | -160 |            | V                   |
| $BV_{EBO}$                 | Emitter-Base Breakdown Voltage                       | $I_C = -10\mu\text{A}, I_C = 0$   | -5.0 |            | V                   |
| $I_{CBO}$                  | Collector Cut-off Current                            | $V_{CB} = -120\text{V}, I_E = 0$<br>$V_{CB} = -120\text{V}, I_E = 0, T_a = 100^\circ\text{C}$ |      | -50<br>-50 | nA<br>$\mu\text{A}$ |
| $I_{EBO}$                  | Emitter Cut-off Current                              | $V_{EB} = -3.0\text{V}, I_C = 0$  |      | -50        | nA                  |
| <b>On Characteristics*</b> |  |   |      |            |                     |
| $h_{FE1}$                  | DC Current Gain                                      | $V_{CE} = -5\text{V}, I_C = -1\text{mA}$  | 50   |            |                     |
| DIVID1                     | Variation Ratio of $h_{FE1}$ Between Die 1 and Die 2 | $h_{FE1}(\text{Die1})/h_{FE1}(\text{Die2})$   | 0.9  | 1.1        |                     |
| $h_{FE2}$                  | DC Current Gain                                      | $V_{CE} = -5\text{V}, I_C = -10\text{mA}$   | 60   | 240        |                     |
| DIVID2                     | Variation Ratio of $h_{FE2}$ Between Die 1 and Die 2 | $h_{FE2}(\text{Die1})/h_{FE2}(\text{Die2})$   | 0.95 | 1.05       |                     |
| $h_{FE3}$                  | DC Current Gain                                      | $V_{CE} = -5\text{V}, I_C = -50\text{mA}$   | 50   |            |                     |
| DIVID3                     | Variation Ratio of $h_{FE3}$ Between Die 1 and Die 2 | $h_{FE3}(\text{Die1})/h_{FE3}(\text{Die2})$   | 0.9  | 1.1        |                     |

**Electrical Characteristics** (Continued)  $T_C = 25^\circ\text{C}$  unless otherwise noted

| Symbol                              | Parameter   | Conditions  | Min.         | Max      | Units  |
|-------------------------------------|---|---|--------------|----------|--------|
| $V_{CE(sat)}$                       | Collector-Emitter Saturation Voltage              | $I_C = -10\text{mA}, I_B = -1\text{mA}$<br>$I_C = -50\text{mA}, I_B = -5\text{mA}$                                | -0.2<br>-0.5 | V<br>V   |        |
| $V_{BE(sat)}$                       | Base-Emitter Saturation Voltage                   | $I_C = -10\text{mA}, I_B = -1\text{mA}$<br>$I_C = -50\text{mA}, I_B = -5\text{mA}$                                |              | -1<br>-1 | V<br>V |
| $V_{BE(on)}$                        | Base-Emitter On Voltage                           | $V_{CE} = -5\text{V}, I_C = -10\text{mA}$   |              | -1       | V      |
| DEL                                 | Difference of $V_{BE(on)}$ Between Die1 and Die 2 | $V_{BE(on)}(\text{Die1}) - V_{BE(on)}(\text{Die2})$   | -8           | 8        | mV     |
| <b>Small Signal Characteristics</b> |   |   |              |          |        |
| $f_T$                               | Current Gain Bandwidth Product                    | $V_{CE} = -10\text{V}, I_C = -10\text{mA}$<br>$f = 100\text{MHz}$   | 100          | 300      | MHz    |
| $C_{ob}$                            | Output Capacitance                                | $V_{CB} = -10\text{V}, I_E = 0, f = 1\text{MHz}$  |              | 6.0      | pF     |
| NF                                  | Noise Figure                                      | $V_{CE} = -5.0\text{V}, I_C = -250\mu\text{A}$ ,<br>$R_S = 1.0\text{K}\Omega, f = 10\text{Hz to } 15.7\text{KHz}$ |              | 8.0      | dB     |

\* Pulse Test: Pulse Width  $\leq 300\text{ms}$ , Duty Cycle  $\leq 2.0\%$

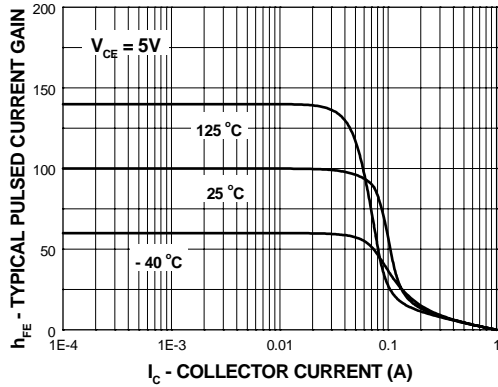
**Thermal Characteristics**  $T_C = 25^\circ\text{C}$  unless otherwise noted

| Symbol          | Parameter                                      | Value | Units              |
|-----------------|--|-------|--------------------|
| $P_D$           | Total Device Dissipation                       | 700   | mW                 |
| $R_{\theta JA}$ | Thermal Resistance, Junction to Ambient, Total | 180   | $^\circ\text{C/W}$ |

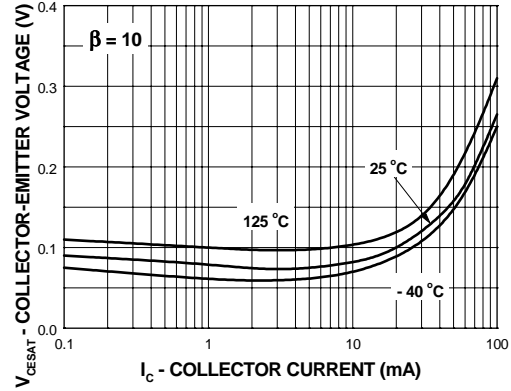
\* Device mounted on a 1 in 2 pad of 2 oz copper

## Typical Performance Characteristics

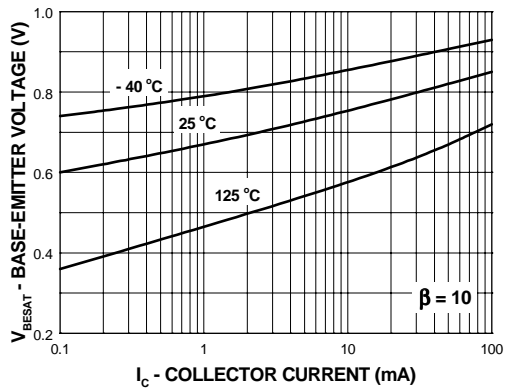
**Figure 1. Typical Pulsed Current Gain vs Collector Current**



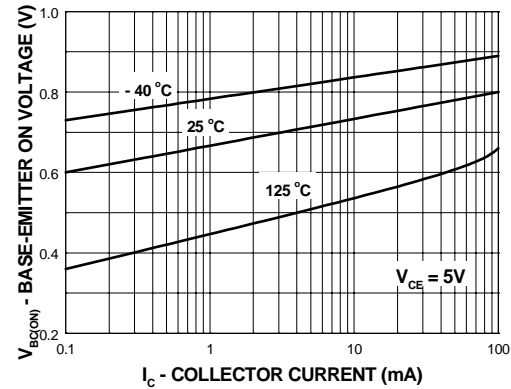
**Figure 2. Collector-Emitter Saturation Voltage vs Collector Current**



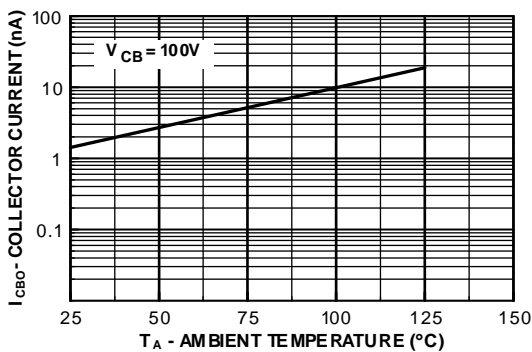
**Figure 3. Base-Emitter Saturation Voltage vs Collector Current**



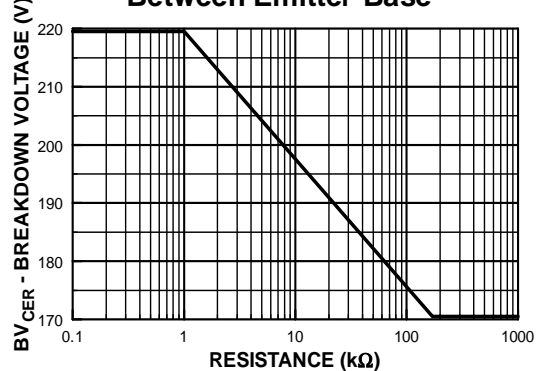
**Figure 4. Base-Emitter On Voltage vs Collector Current**



**Figure 5. Collector-Cutoff Current vs Ambient Temperature**

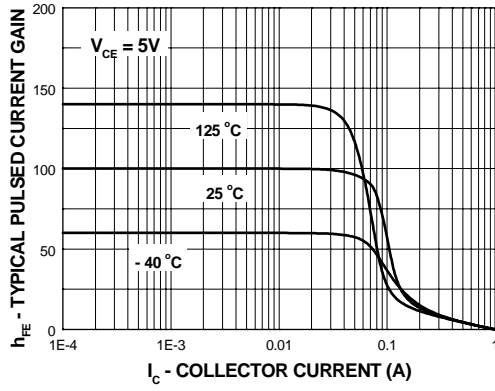


**Figure 6. Collector-Emitter Breakdown Voltage with Resistance Between Emitter-Base**



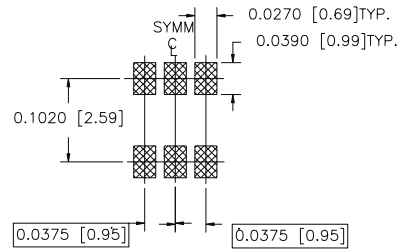
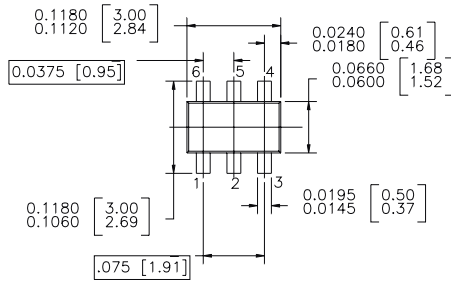
Typical Performance Characteristics (Continued)

Figure 7. Input and Output Capacitance vs Reverse Voltage

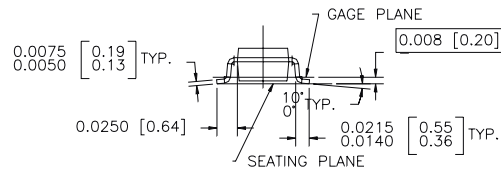
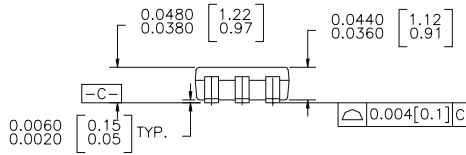


## Mechanical Dimensions

# SuperSOT™-6



CONTROLLING DIMENSION IS INCH  
VALUES IN [ ] ARE MILLIMETERS



NOTES : UNLESS OTHERWISE SPECIFIED

1.0 STANDARD LEAD FINISH : 150 MICRONS 93.81 MICROMETERS)  
MINIMUM TIN / LEAD (SOLDER) ON COPPER.

2.0 NO JEDEC REGISTRATION AS OF JULY 1996

SUPER SOT 6 LEADS

Dimensions in Millimeters

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| ActiveArray™                         | FAST <sup>r</sup> ™ | ISOPANAR™              | Power247™                    | Stealth™               |
| Bottomless™                          | FPS™                | LittleFET™             | PowerEdge™                   | SuperFET™              |
| CoolFET™                             | FRFET™              | MICROCOUPLER™          | PowerSaver™                  | SuperSOT™-3            |
| CROSSVOLT™                           | GlobalOptoisolator™ | MicroFET™              | PowerTrench <sup>®</sup>     | SuperSOT™-6            |
| DOME™                                | GTO™                | MicroPak™              | QFET <sup>®</sup>            | SuperSOT™-8            |
| EcoSPARK™                            | HiSeC™              | MICROWIRE™             | QS™                          | SyncFET™               |
| E <sup>2</sup> CMOST™                | I <sup>2</sup> C™   | MSX™                   | QT Optoelectronics™          | TinyLogic <sup>®</sup> |
| EnSigna™                             | <i>i-Lo</i> ™       | MSXPro™                | Quiet Series™                | TINYOPTO™              |
| FACT™                                | ImpliedDisconnect™  | OCX™                   | RapidConfigure™              | TruTranslation™        |
| FACT Quiet Series™                   |                     | OCXPro™                | RapidConnect™                | UHC™                   |
| Across the board. Around the world.™ |                     | OPTOLOGIC <sup>®</sup> | $\mu$ SerDes™                | UltraFET <sup>®</sup>  |
| The Power Franchise <sup>®</sup>     |                     | OPTOPLANAR™            | SILENT SWITCHER <sup>®</sup> | UniFET™                |
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2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

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|--------------------------|------------------------|---|
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